	Material Comp © Copyright 2005. I international and Par	osition Dee PC, Bannockt	claration ourn, Illinois. <i>A</i> opyright conve	All rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the encompass	substances ses all lowe	within the er level mat	manufacture erials for wh	er listed it hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard For				Form Type Distribute					eous Materia	rials and Mfg Information				
Supplier	· Information														
Company name* Co				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-01			
Contact N	ame	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-H	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-H	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item N BYW80-20		Number Mfr Item Name				Effective Date	Version	Version Manufacturing Site		ing Site	V	Weight*	UOM	Unit Type
			-200G	G REC T0220 7A 200V ULTFST			2024-05-01 CN5			1962.01		mg	Each		
/lanufa	cturing Proccess Informa	tion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 I		J-STD-020 MSI	L Rating	Peak Process Body Temperat		ure Max Time at Peak Tempe		Temperat	ure Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 s		second	ds 3					
omments															
or more i	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	А	Lead (Pb)	7439-92-1	7a	74.682	mg
			Supplier	Tin (Sn)	7440-31-5		8.298	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9	mg		Metal Hydroxide	proprietary data		38.073	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.925	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		81.585	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		13.5975	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted)